

RF Probing Solutions

- Manual, Semiautomatic & Fully Automatic Versions
 - Standard and Vacuum Systems - DC to > 750 GHz
 - Silicon and III-V materials - die, partial wafers, wafers up to 300 mm, frames, MMICS, T/R modules and more.
- Thermal Systems from -60 C to 300 C
- Thin Wafer Material Handling
- Customized Chucks, Carrier Plates, Chip Trays
- Manipulators – large family - manual & programmable
- Non-Contact Height Measurement Sensors
- DC & RF Probe Tips, Probe Cards, Multi-Contact Wedges
- Accessories – calibration substrates, cleaning pads, cables, connectors
- Integrated Solutions – VNAs, Extension Modules and tuners
- Modular PS4L Hardware & Software Architecture

